

Final Product/Process Change Notification

Document #:FPCN25300Z Issue Date:26 Oct 2023

Title of Change:	Transfer of DSN2 Schottky plating site (from FCMS, China to HTKS, China) & Back End sites consolidation (from JCAP, MYD to JCAP)
Proposed Changed Material First Ship Date:	26 Apr 2024 or earlier if approved by customer
Current Material Last Order Date:	N/A Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.
Current Material Last Delivery Date:	N/A The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory
Product Category:	Active components – Discrete components
Contact information:	Contact your local onsemi Sales Office or NurulAliaFatin.Redzoan@onsemi.com
PCN Samples Contact:	Contact your local onsemi Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Sample Availability Date:	21 Aug 2023
PPAP Availability Date:	04 Sep 2023
Additional Reliability Data:	Contact your local onsemi Sales Office or NurulAkmar.MohdFauzi@onsemi.com
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. The change will be implemented at 'Proposed Change Material First Ship Date' in compliance to J-STD-46 or ZVEI, or earlier upon customer approval, or per our signed agreements. onsemi will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com.
Change Category	
Category	Type of Change
Data Sheet	Correction of data sheet / errata
Process - Assembly	Move of all or part of assembly to a different location/site/subcontractor., Change of product marking

Description and Purpose:

Due to the acquisition of FCMS, China by HTKS, China FCMS will discontinue their support by Oct'2023. Therefore, **onsemi** is notifying its customer of its intent to transfer the plating site from external foundry facility, Flipchip Millenium (FCMS), China to external foundry facility, Huatian Technology (HTKS), China. Additionally, the back-end sites will be consolidated to JCET Jiangyn (AVM) (JCAP), China.

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		Before Change Description	1	After Change Description	
Backgrind Site		onsemi ISMF, Malaysia		Huatian Technology, China	
Marking Design		(0.400)	EAMS 5F40 YYY	DSN2 (0402) CASE 152AC AC = Specific Device Code M = Month Code Notes : Device marking code will be different based on OPN.	
Plating Site	Flipch	chip Millenium (Shanghai)(FCMS), China		Huatian Technology, China	
Probe, Tape & Reel Site	J	onsemi Seremban, Malaysia JCET Jiangyn BE(AVM) (JCAP), China		JCET Jiangyn BE(AVM)(JCAP), China	
Reason / Motivation for (Change:	Acquisition			
Anticipated impact on fit, form, function, reliability, product safety or manufacturability: The device has been of successfully passed the performed by onsemination of the device has been of successfully passed the performed by onsemination of the device has been of successfully passed the performed by onsemination of the device has been of successfully passed the performed by onsemination of the device has been of successfully passed the performed by onsemination of the device has been of successfully passed the performed by onsemination of the device has been of successfully passed the performed by onsemination of the device has been of successfully passed the performed by onsemination of the device has been of successfully passed the performed by onsemination of the device has been of successfully passed the performed by onsemination of the device has been of successfully passed the performed by onsemination of the device has been of the performed by onsemination of the device has been of th		The device has been qualified successfully passed the quali	fication tests. P	based on the same Product Specification. The device ha otential impacts can be identified, but due to testing associated risks are verified and excluded.	
Sites Affected:					
onsemi Sites		External Foundry/Subcon Sites			
None		Huatian Technology, China			
		JCAP, China			
Marking of Parts/ Traceal Change:	oility of	Affected products will be identified by date code			

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Reliability Data Summary:

QV DEVICE NAME: NSVR05F40NXT5G

RMS: S89608

PACKAGE: DSN2 (0402)

Test	Specification	Condition	Interval	Results
High Temperature Storage Life	JESD22-A103	Ta= 125°C	1008 hrs	0/231
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260 °C		0/231
Temperature Cycling	JESD22-A104	Ta= -40°C to +125°C	850 cyc	0/231
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231

NOTE: AEC-1pager and Change table are attached.

To view attachments:

- 1. Download pdf copy of the PCN to your computer
- 2. Open the downloaded pdf copy of the PCN
- 3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field
- 4. Then click on the attached file/s

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the <u>PCN Customized Portal</u>.

Current Part Number	New Part Number	Qualification Vehicle
NSVR05F40NXT5G	N/A	NSVR05F40NXT5G

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